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(54) Title: PROCESS FOR FABRICATING CIRCUIT ASSEMBLIES USING ELECTRODEPOSITABLE DIELECTRIC COATING COMPOSITIONS

(57) Abstract: Provided is a process for forming metallized vias in a substrate including the steps of (I) applying to an electroconductive substrate an electrodepositable coating composition onto all exposed surfaces of the substrate to form a conformal dielectric coating; (II) ablating a surface of the dielectric coating to expose a section of the substrate; (III) applying a layer of metal to all surfaces to form metallized vias in the substrate. Also disclosed are processes for fabricating a circuit assembly which include the application of an electrodoepositable coating composition onto exposed surfaces of the substrate/core to form a conformal dielectric coating thereon. The electrodepositable coating composition includes a resinous phase dispersed in an aqueous phase, where the resinous phase has a covalently bonded halogen content of at least 1 percent by weight. The dielectric coating derived therefrom has a low dielectric constant and low dielectric loss factor.